

HAT1024R

Silicon P Channel Power MOS FET High Speed Power Switching

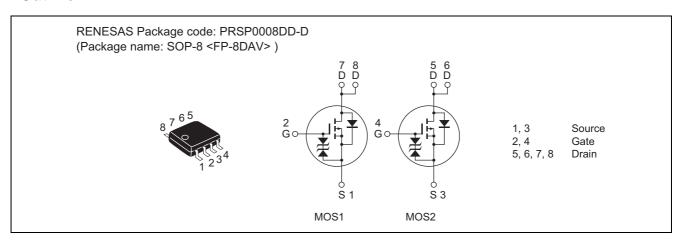
REJ03G1146-0900 (Previous: ADE-208-476G)

> Rev.9.00 Sep 07, 2005

Features

- Low on-resistance
- Capable of 4 V gate drive
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	-3.5	Α
Drain peak current	I _{D (pulse)} Note 1	-28	Α
Body-drain diode reverse drain current	I _{DR}	-3.5	А
Channel dissipation	Pch Note 2	2	W
Channel dissipation	Pch Note 3	3	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 2. 1 Drive operation: When using the glass epoxy board (FR4 $40 \times 40 \times 1.6$ mm), PW ≤ 10 s
- 3. 2 Drive operation: When using the glass epoxy board (FR4 $40 \times 40 \times 1.6$ mm), PW ≤ 10 s

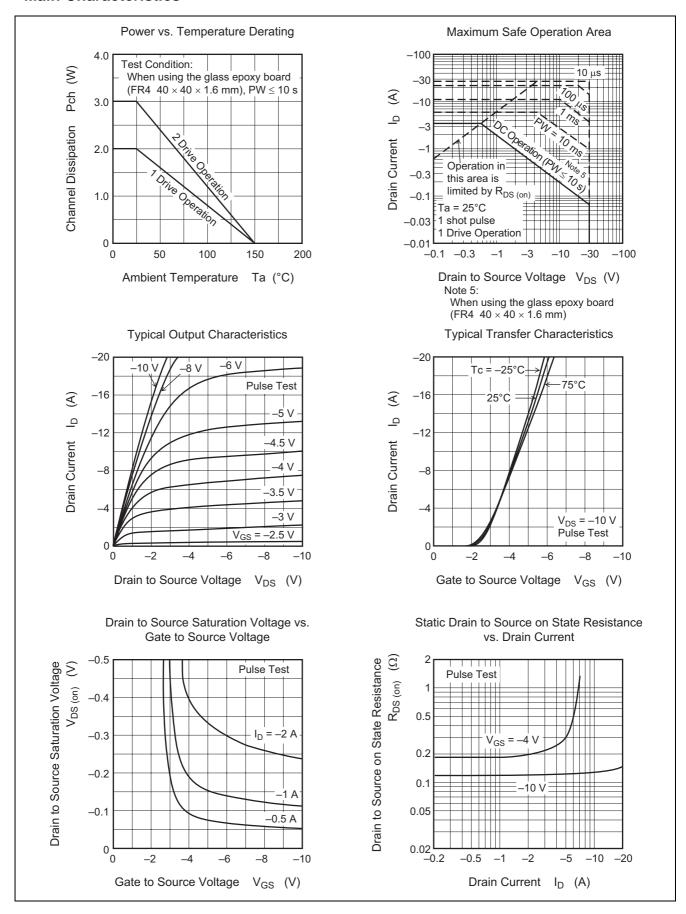
Electrical Characteristics

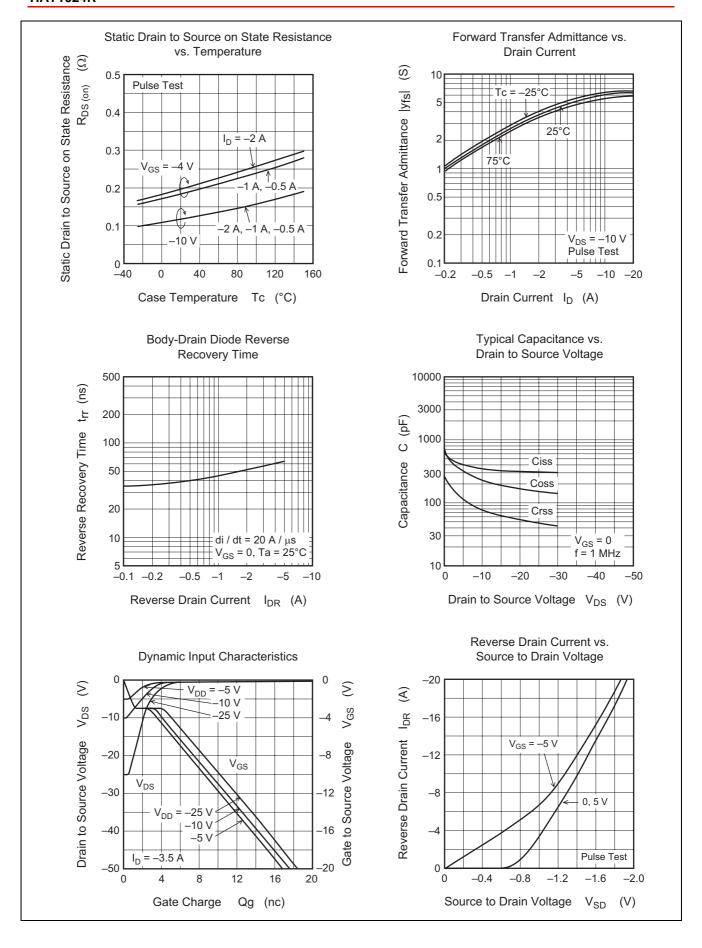
 $(Ta = 25^{\circ}C)$

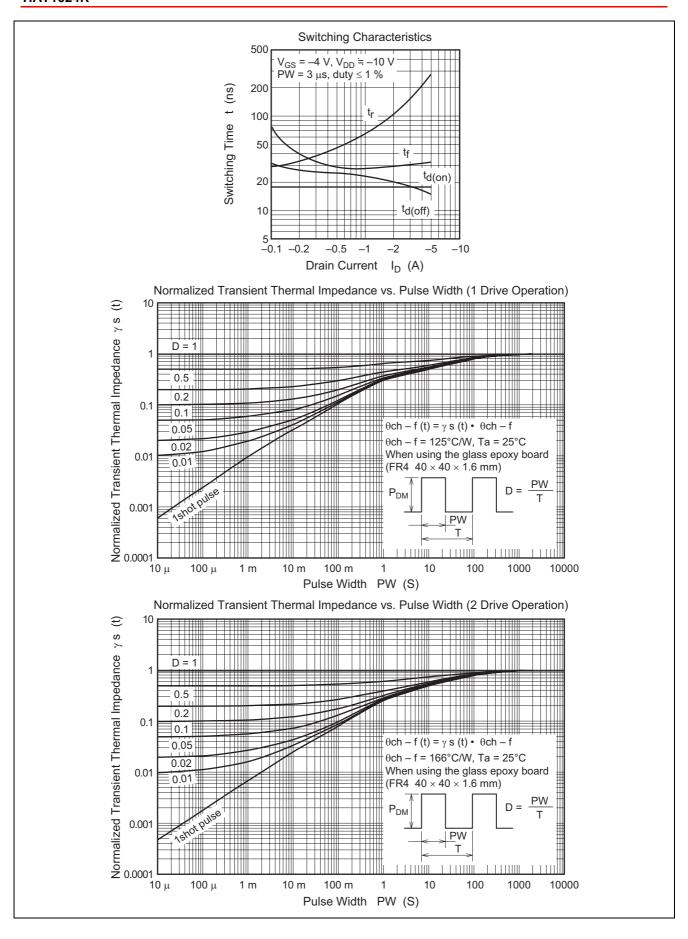
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	-30	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _(BR) GSS	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-10	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	_	-2.5	V	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}		0.12	0.16	Ω	$I_D = -2 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	0.2	0.34	Ω	$I_D = -2 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	2.5	3.5	_	S	$I_D = -2 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	350	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	230	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	75	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	18	_	ns	$V_{GS} = -4 \text{ V}, I_D = -2 \text{ A},$
Rise time	t _r	_	110	_	ns	V _{DD} ≅ −10 V
Turn-off delay time	t _{d (off)}	_	20	_	ns	
Fall time	t _f	_	30	_	ns	
Body-drain diode forward voltage	V_{DF}	_	-1.0	-1.5	V	$I_F = -3.5 \text{ A}, V_{GS} = 0$ Note 4
Body-drain diode reverse recovery time	t _{rr}	_	60	_	ns	$I_F = -3.5 \text{ A}, V_{GS} = 0$
						$di_F/dt = 20 A/\mu s$

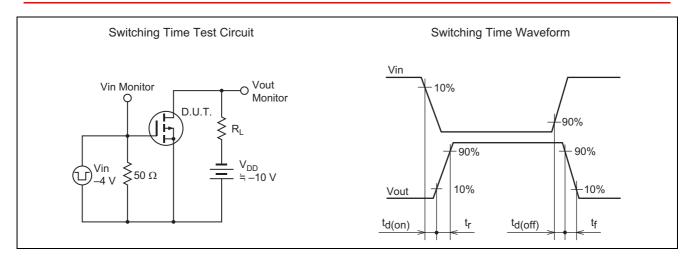
Note: 4. Pulse test

Main Characteristics

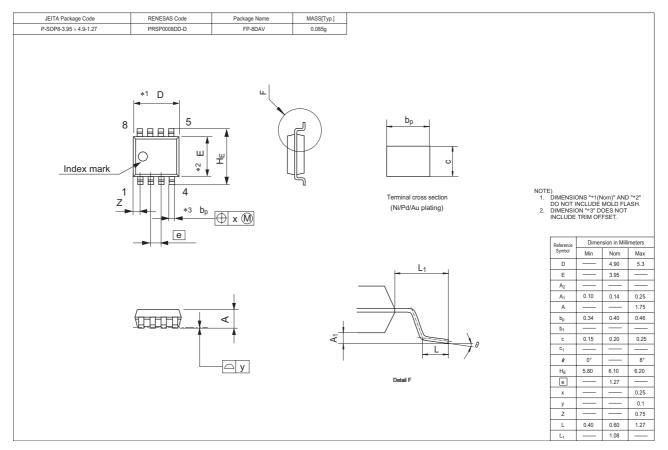








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1024R-EL-E	2500 pcs	Taping

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